

1. Scope

This specification applies to DVRF00106, RF Isolator.  
 Document revision: B

2. Product Description and Identification (Part Number)

- 1) Description: Isolator
- 2) Product Identification (Part Number): DVRF00106
- 3) Direction: Clockwise, see Fig 2-1.

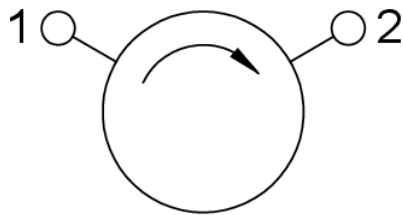


Fig. 2-1

3. Electrical Characteristics

Parameter	Test Conditions	Min	Typ	Max	Units
Frequency range		617		652	MHz
Operating temperature		-40		+125	°C
Storage temperature range		-40		+125	°C
Average Power				100	W
Reverse Power	Up to 10 minutes with base temperature of 210°C			80	W
Maximum Power				600	W
Impedance			50		Ω
Insertion Loss				0.30	dB
Isolation		20			dB
Return Loss		20			dB

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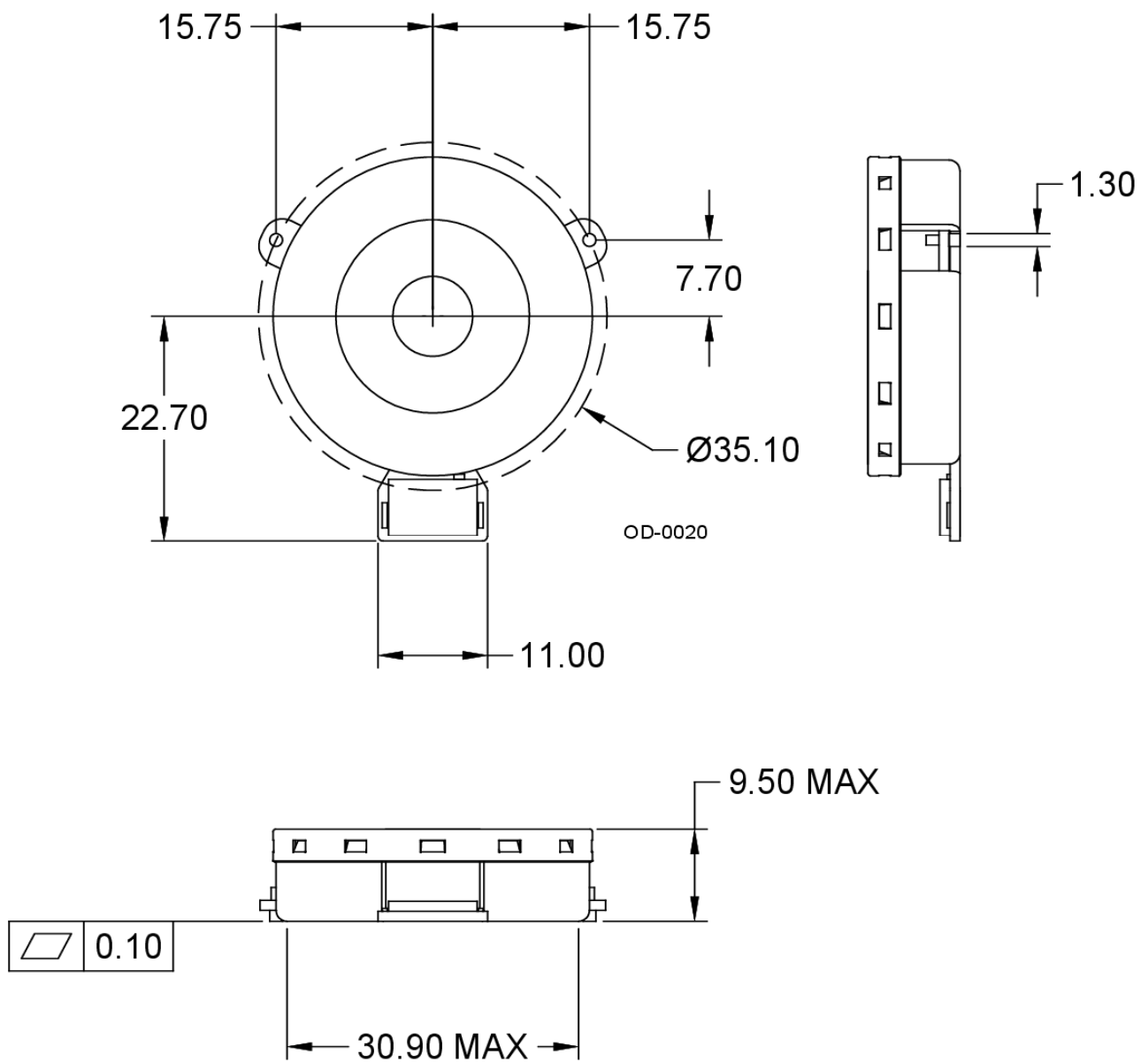
Intermodulation distortion	2 x 40W CW tones, 5MHz spacing			-75	dBc
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- a) Electrical Characteristics apply over the operating temperature range unless otherwise specified.
- b) Exceeding any of the limits listed here may result in permanent damage to the device or may reduce device reliability.
- c) Test fixture PCB is Rogers 4350B, 0.50mm thick.

4. Shape and Dimensions

- 1) Dimensions see Fig 4-1.
- 2) All dimensions are in mm.
- 3) Tolerance is  $\pm 0.20\text{mm}$  unless otherwise indicated.
- 4) Pins and housing are silver (Ag) plated.
- 5) This device is RoHS compliant.

Fig. 4-1



## 5. Packaging

- 1) Devices are packed in tape & reel.

## 6. Recommended Soldering Technologies

### 6.1 Re-flowing Profile

- △ Preheat condition: 150 ~200°C/60~120sec.
- △ Allowed time above 217°C: 60~90sec.
- △ Max temp: 260°C
- △ Max time at max temp: 10sec.
- △ Solder paste: Sn/3.0Ag/0.5Cu
- △ Allowed Reflow time: 2x max

[Note: The reflow profile in the above table is only for qualification and is not meant to specify board assembly profiles. Actual board assembly profiles must be based on the customer's specific board design, solder paste and process, and should not exceed the parameters as the Reflow profile shows.]

